

ABSTRACT

There is provided a method for manufacturing a flat printed wiring board in which spaces between circuit patterns are filled with a resin. The method comprises: laminating via a mold release film a plurality of sets of laminated bodies formed by superposing a semi-cured resin sheet on a printed wiring board with circuit patterns formed thereon; placing the laminated plural sets of the laminated bodies interposed between a pair of smoothing plates and collectively pressing the laminated bodies in a reduced pressure atmosphere used for curing the resin; and then polishing the cured resin covering the circuit patterns, thereby exposing the circuit patterns.